

Specifications

Insulation Resistance: 1,000MΩ min. at 500V DC
 Dielectric Withstanding Voltage: 500V AC for 1 minute
 Contact Resistance: 30mΩ max. at 10mA/20mV max.
 Operating Temperature Range: -40°C to +170°C
 Contact Force: 20g min. per pin at minimum displacement of 0.3mm
 80g max. per pin at maximum displacement of 0.7mm
 Mating Cycles: 10,000 insertions min.

Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Features

Open Top type sockets for BQFP packages

Part Number (Details)

IC211 - 164 4 - 003 * - *

Series No.

No. of Contact Pins

Number of Sides with Contacts

Design Number

Positioning Pin:

N = Without Positioning Pin

Unmarked = With Positioning Pin

Protection Key*

K = With Protection Key

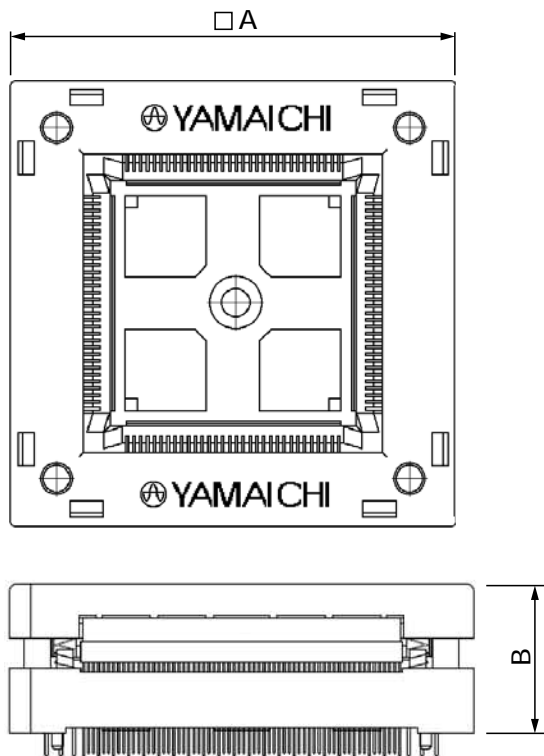
Unmarked = Without Protection Key

**Protection Key: Prevents IC from releasing during transportation

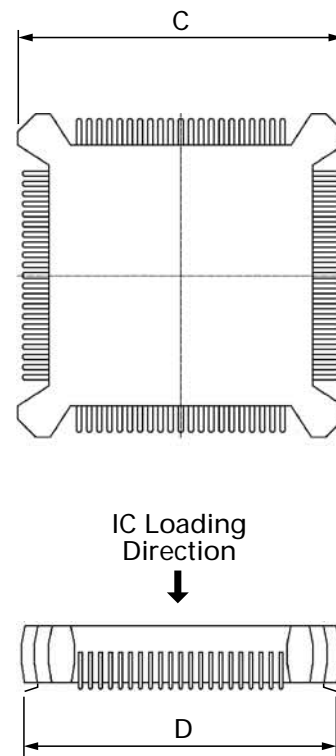


Applicable Dimensions (Reference Only)

Outline Socket Dimensions



Outline IC Dimensions

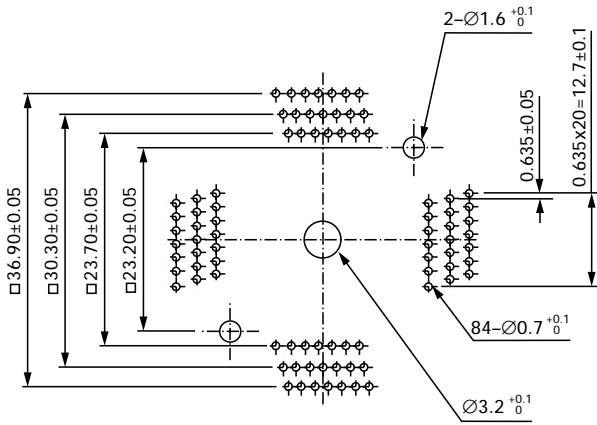


Part Number	Pin Count	Pitch	Socket Dimensions		IC Dimensions	
			□A	B	C	D
IC211-0844-001 *-*	84	0.635	39.80	16.0	20.40	19.80
IC211-1004-004 *-*	100	0.635	42.40	16.0	22.94	22.40
IC211-1324-002 *-*	132	0.635	47.40	16.0	28.02	27.40
IC211-1644-003 *-*	164	0.635	52.50	16.0	33.10	32.50

Recommended PCB Layouts (Reference Only)

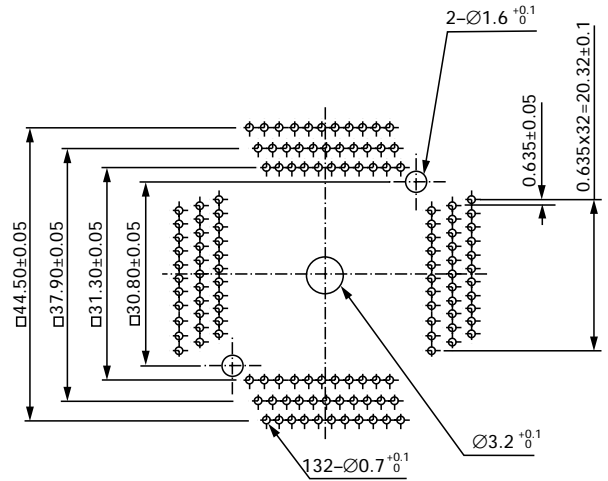
84 pins

IC211-0844-001



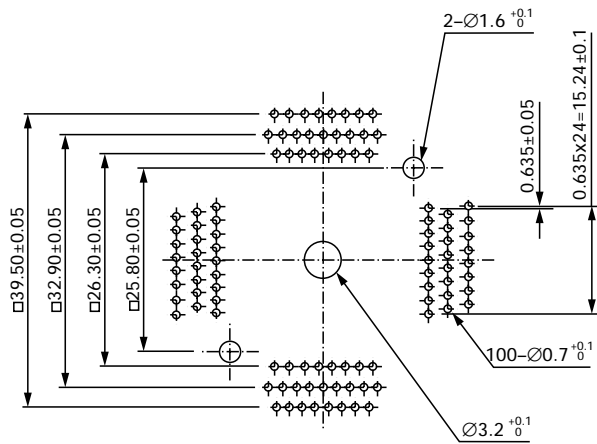
132 pins

IC211-1324-002



100 pins

IC211-1004-004



164 pins

IC211-1644-003

